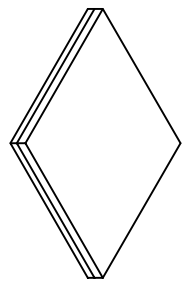


MANUFACTURED TO THE REQUIREMENTS OF MIL-01

REWORKED TO THE REQUIREMENTS OF MIL-01

REV	DATE	DESCRIPTION	DESIGNED BY	MANUFACTURED BY	DATE
01	09/05/00	INITIAL RELEASE	RKR/UT	RKR/UT	09/05/00



7. REFERENCE SPECIFICATIONS:  
 A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.  
 B. AAWW SPEC #001-0519-2062: MARKING.
6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 225.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 15 X 15.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

APPROVALS	DATE	APPROVALS	DATE	APPROVALS	DATE	APPROVALS	DATE
DESIGNED BY: SIERO	06/12/00	APPROVED BY: [Signature]	06/12/00	MANUFACTURED BY: [Signature]	09/05/00	INSPECTED BY: [Signature]	09/05/00
DRAWN BY: DARRIO	06/12/00	APPROVED BY: [Signature]	06/12/00	MANUFACTURED BY: [Signature]	09/05/00	INSPECTED BY: [Signature]	09/05/00
CHECKED BY: [Signature]	06/12/00	APPROVED BY: [Signature]	06/12/00	MANUFACTURED BY: [Signature]	09/05/00	INSPECTED BY: [Signature]	09/05/00
DATE: 06/12/00		DATE: 06/12/00		DATE: 09/05/00		DATE: 09/05/00	



FORM NO. 000001-000

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